

MATERIAL DECLARATION SHEET



Material Number	CMH322522 Series			
Product Line	Chip Inductor			
Compliance Date	2014/05/27			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite body	Ferrite Ni-Zn Series	0.0288	Iron oxide	1309-37-1	62.0	40.92	66.00
				Nickel oxide	1313-99-1	11.0	7.26	
				Zinc oxide	1314-13-2	20.0	13.20	
				Copper oxide	1317-38-0	7.0	4.62	
2	Molding Compound	Phenolic Molding Compound	0.0044	Phenol-formaldehyde resin	9003-35-4	30.0	3.00	10.00
				Fiber Glass	65997-17-3	65.0	6.50	
				Carbon black	1333-86-4	5.0	0.50	
3	Copper/ Coating	Copper Wire	0.0052	Copper	7440-50-8	96.5	14.475	15.00
		Polyurethane-Based Insulation Varnish	0.0013	Polyamideimide Resin	31957-38-1	3.5	0.525	
4	Terminal-Clip	Copper_C1100	0.0022	Copper	7440-50-8	100.0	5.00	5.00
5	Solder	Lead Free Solder	0.0004	Tin	7440-31-5	100.0	1.00	1.00
6	Adhesive	EPOXY_ME-5890LC	0.0009	Epoxy resin	24969-06-0	100.0	2.00	2.00
7	Marking	Printer INK	0.0004	Carbon Black	1333-86-4	100.0	1.00	1.00
			Total weight	0.0436				

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